

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L30	0	method attaching semiconductor assembly comprising device active surface first end second lateral side substrate upper wall applying silane- based material layer one portion connecting faces flowable underfill between contacts	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/01/29 19:15

1/ 29/ 2009 7:15:28 PM

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